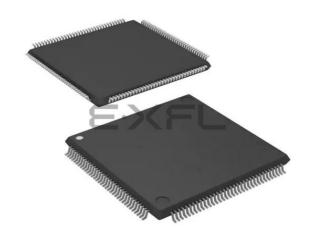
E·XFL

Intel - EPM7256AETC144-10 Datasheet



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Understanding <u>Embedded - CPLDs (Complex</u> <u>Programmable Logic Devices)</u>

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixedfunction ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	10 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	16
Number of Macrocells	256
Number of Gates	5000
Number of I/O	120
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	144-LQFP
Supplier Device Package	144-TQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm7256aetc144-10

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Table 1. MAX 700	OA Device Featur	es			
Feature	EPM7032AE	EPM7064AE	EPM7128AE	EPM7256AE	EPM7512AE
Usable gates	600	1,250	2,500	5,000	10,000
Macrocells	32	64	128	256	512
Logic array blocks	2	4	8	16	32
Maximum user I/O pins	36	68	100	164	212
t _{PD} (ns)	4.5	4.5	5.0	5.5	7.5
t _{SU} (ns)	2.9	2.8	3.3	3.9	5.6
t _{FSU} (ns)	2.5	2.5	2.5	2.5	3.0
t _{CO1} (ns)	3.0	3.1	3.4	3.5	4.7
f _{CNT} (MHz)	227.3	222.2	192.3	172.4	116.3

...and More Features

- 4.5-ns pin-to-pin logic delays with counter frequencies of up to 227.3 MHz
- MultiVolt[™] I/O interface enables device core to run at 3.3 V, while I/O pins are compatible with 5.0-V, 3.3-V, and 2.5-V logic levels
- Pin counts ranging from 44 to 256 in a variety of thin quad flat pack (TQFP), plastic quad flat pack (PQFP), ball-grid array (BGA), spacesaving FineLine BGA[™], and plastic J-lead chip carrier (PLCC) packages
- Supports hot-socketing in MAX 7000AE devices
- Programmable interconnect array (PIA) continuous routing structure for fast, predictable performance
- PCI-compatible
- Bus-friendly architecture, including programmable slew-rate control
- Open-drain output option
- Programmable macrocell registers with individual clear, preset, clock, and clock enable controls
- Programmable power-up states for macrocell registers in MAX 7000AE devices
- Programmable power-saving mode for 50% or greater power reduction in each macrocell
- Configurable expander product-term distribution, allowing up to 32 product terms per macrocell
- Programmable security bit for protection of proprietary designs
- 6 to 10 pin- or logic-driven output enable signals
- Two global clock signals with optional inversion
- Enhanced interconnect resources for improved routability
- Fast input setup times provided by a dedicated path from I/O pin to macrocell registers
- Programmable output slew-rate control
- Programmable ground pins

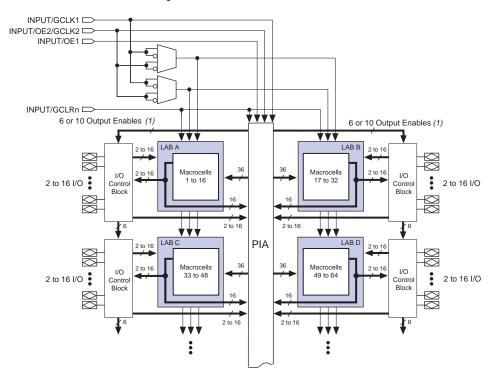


Figure 1. MAX 7000A Device Block Diagram

Note:

(1) EPM7032AE, EPM7064AE, EPM7128A, EPM7128AE, EPM7256A, and EPM7256AE devices have six output enables. EPM7512AE devices have 10 output enables.

Logic Array Blocks

The MAX 7000A device architecture is based on the linking of high-performance LABs. LABs consist of 16-macrocell arrays, as shown in Figure 1. Multiple LABs are linked together via the PIA, a global bus that is fed by all dedicated input pins, I/O pins, and macrocells.

Each LAB is fed by the following signals:

- **3**6 signals from the PIA that are used for general logic inputs
- Global controls that are used for secondary register functions
- Direct input paths from I/O pins to the registers that are used for fast setup times

For registered functions, each macrocell flipflop can be individually programmed to implement D, T, JK, or SR operation with programmable clock control. The flipflop can be bypassed for combinatorial operation. During design entry, the designer specifies the desired flipflop type; the Altera software then selects the most efficient flipflop operation for each registered function to optimize resource utilization.

Each programmable register can be clocked in three different modes:

- Global clock signal. This mode achieves the fastest clock-to-output performance.
- Global clock signal enabled by an active-high clock enable. A clock enable is generated by a product term. This mode provides an enable on each flipflop while still achieving the fast clock-to-output performance of the global clock.
- Array clock implemented with a product term. In this mode, the flipflop can be clocked by signals from buried macrocells or I/O pins.

Two global clock signals are available in MAX 7000A devices. As shown in Figure 1, these global clock signals can be the true or the complement of either of the global clock pins, GCLK1 or GCLK2.

Each register also supports asynchronous preset and clear functions. As shown in Figure 2, the product-term select matrix allocates product terms to control these operations. Although the product-term-driven preset and clear from the register are active high, active-low control can be obtained by inverting the signal within the logic array. In addition, each register clear function can be individually driven by the active-low dedicated global clear pin (GCLRn). Upon power-up, each register in a MAX 7000AE device may be set to either a high or low state. This power-up state is specified at design entry. Upon power-up, each register in EPM7128A and EPM7256A devices are set to a low state.

All MAX 7000A I/O pins have a fast input path to a macrocell register. This dedicated path allows a signal to bypass the PIA and combinatorial logic and be clocked to an input D flipflop with an extremely fast (as low as 2.5 ns) input setup time.

Open-Drain Output Option

MAX 7000A devices provide an optional open-drain (equivalent to open-collector) output for each I/O pin. This open-drain output enables the device to provide system-level control signals (e.g., interrupt and write enable signals) that can be asserted by any of several devices. This output can also provide an additional wired-OR plane.

Open-drain output pins on MAX 7000A devices (with a pull-up resistor to the 5.0-V supply) can drive 5.0-V CMOS input pins that require a high V_{IH} . When the open-drain pin is active, it will drive low. When the pin is inactive, the resistor will pull up the trace to 5.0 V to meet CMOS V_{OH} requirements. The open-drain pin will only drive low or tri-state; it will never drive high. The rise time is dependent on the value of the pull-up resistor and load impedance. The I_{OL} current specification should be considered when selecting a pull-up resistor.

Programmable Ground Pins

Each unused I/O pin on MAX 7000A devices may be used as an additional ground pin. In EPM7128A and EPM7256A devices, utilizing unused I/O pins as additional ground pins requires using the associated macrocell. In MAX 7000AE devices, this programmable ground feature does not require the use of the associated macrocell; therefore, the buried macrocell is still available for user logic.

Slew-Rate Control

The output buffer for each MAX 7000A I/O pin has an adjustable output slew rate that can be configured for low-noise or high-speed performance. A faster slew rate provides high-speed transitions for high-performance systems. However, these fast transitions may introduce noise transients into the system. A slow slew rate reduces system noise, but adds a nominal delay of 4 to 5 ns. When the configuration cell is turned off, the slew rate is set for low-noise performance. Each I/O pin has an individual EEPROM bit that controls the slew rate, allowing designers to specify the slew rate on a pin-by-pin basis. The slew rate control affects both the rising and falling edges of the output signal.

MAX 7000A Programmable Logic Device Data Sheet

Notes to tables:

- (1) See the Operating Requirements for Altera Devices Data Sheet.
- (2) Minimum DC input voltage is -0.5 V. During transitions, the inputs may undershoot to -2.0 V for input currents less than 100 mA and periods shorter than 20 ns.
- (3) For EPM7128A and EPM7256A devices only, V_{CC} must rise monotonically.
- (4) In MAX 7000AE devices, all pins, including dedicated inputs, I/O pins, and JTAG pins, may be driven before V_{CCINT} and V_{CCIO} are powered.
- (5) These devices support in-system programming for -40° to 100° C. For in-system programming support between -40° and 0° C, contact Altera Applications.
- (6) These values are specified under the recommended operating conditions shown in Table 14 on page 28.
- (7) The parameter is measured with 50% of the outputs each sourcing the specified current. The I_{OH} parameter refers to high-level TTL or CMOS output current.
- (8) The parameter is measured with 50% of the outputs each sinking the specified current. The I_{OL} parameter refers to low-level TTL or CMOS output current.
- (9) This value is specified for normal device operation. For MAX 7000AE devices, the maximum leakage current during power-up is $\pm 300 \ \mu$ A. For EPM7128A and EPM7256A devices, leakage current during power-up is not specified.
- (10) For EPM7128A and EPM7256A devices, this pull-up exists while a device is programmed in-system.
- (11) For MAX 7000AE devices, this pull-up exists while devices are programmed in-system and in unprogrammed devices during power-up.
- (12) Capacitance is measured at 25 °C and is sample-tested only. The OE1 pin (high-voltage pin during programming) has a maximum capacitance of 20 pF.
- (13) The POR time for MAX 7000AE devices (except MAX 7128A and MAX 7256A devices) does not exceed 100 μs. The sufficient V_{CCINT} voltage level for POR is 3.0 V. The device is fully initialized within the POR time after V_{CCINT} reaches the sufficient POR voltage level.

Tables 17 through 30 show EPM7032AE, EPM7064AE, EPM7128AE, EPM7256AE, EPM7512AE, EPM7128A, and EPM7256A timing information.

Table 1	7. EPM7032AE External Timi	ng Parameters	Note (1)						
Symbol	Parameter	Conditions			Speed	Grade			Unit	
			-	4	-	7	-1	0	1	
			Min	Max	Min	Max	Min	Max		
t _{PD1}	Input to non-registered output	C1 = 35 pF (2)		4.5		7.5		10	ns	
t _{PD2}	I/O input to non-registered output	C1 = 35 pF (2)		4.5		7.5		10	ns	
t _{SU}	Global clock setup time	(2)	2.9		4.7		6.3		ns	
t _H	Global clock hold time	(2)	0.0		0.0		0.0		ns	
t _{FSU}	Global clock setup time of fast input		2.5		3.0		3.0		ns	
t _{FH}	Global clock hold time of fast input		0.0		0.0		0.0		ns	
t _{CO1}	Global clock to output delay	C1 = 35 pF	1.0	3.0	1.0	5.0	1.0	6.7	ns	
t _{CH}	Global clock high time		2.0		3.0		4.0		ns	
t _{CL}	Global clock low time		2.0		3.0		4.0		ns	
t _{ASU}	Array clock setup time	(2)	1.6		2.5		3.6		ns	
t _{AH}	Array clock hold time	(2)	0.3		0.5		0.5		ns	
t _{ACO1}	Array clock to output delay	C1 = 35 pF (2)	1.0	4.3	1.0	7.2	1.0	9.4	ns	
t _{ACH}	Array clock high time		2.0		3.0		4.0		ns	
t _{ACL}	Array clock low time		2.0		3.0		4.0		ns	
t _{CPPW}	Minimum pulse width for clear and preset	(3)	2.0		3.0		4.0		ns	
t _{CNT}	Minimum global clock period	(2)		4.4		7.2		9.7	ns	
f _{CNT}	Maximum internal global clock frequency	(2), (4)	227.3		138.9		103.1		MHz	
t _{ACNT}	Minimum array clock period	(2)		4.4		7.2		9.7	ns	
f _{ACNT}	Maximum internal array clock frequency	(2), (4)	227.3		138.9		103.1		MHz	

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Symbol	Parameter	Conditions	Speed Grade						
			-	-4		-7		10	
			Min	Max	Min	Max	Min	Max	
t _{IC}	Array clock delay			1.2		2.0		2.5	ns
t _{EN}	Register enable time			0.6		1.0		1.2	ns
t _{GLOB}	Global control delay			0.8		1.3		1.9	ns
t _{PRE}	Register preset time			1.2		1.9		2.6	ns
t _{CLR}	Register clear time			1.2		1.9		2.6	ns
t _{PIA}	PIA delay	(2)		0.9		1.5		2.1	ns
t _{LPA}	Low-power adder	(6)		2.5		4.0		5.0	ns

Symbol	Parameter	Conditions			Speed	Grade			Unit
			-4	4	-	7	-1	0	
			Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non- registered output	C1 = 35 pF (2)		4.5		7.5		10.0	ns
t _{PD2}	I/O input to non- registered output	C1 = 35 pF (2)		4.5		7.5		10.0	ns
t _{SU}	Global clock setup time	(2)	2.8		4.7		6.2		ns
t _H	Global clock hold time	(2)	0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		2.5		3.0		3.0		ns
t _{FH}	Global clock hold time of fast input		0.0		0.0		0.0		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF	1.0	3.1	1.0	5.1	1.0	7.0	ns
t _{CH}	Global clock high time		2.0		3.0		4.0		ns
t _{CL}	Global clock low time		2.0		3.0		4.0		ns
t _{ASU}	Array clock setup time	(2)	1.6		2.6		3.6		ns
t _{AH}	Array clock hold time	(2)	0.3		0.4		0.6		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF (2)	1.0	4.3	1.0	7.2	1.0	9.6	ns
t _{ACH}	Array clock high time		2.0		3.0		4.0		ns
t _{ACL}	Array clock low time		2.0		3.0		4.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(3)	2.0		3.0		4.0		ns
t _{CNT}	Minimum global clock period	(2)		4.5		7.4		10.0	ns
f _{CNT}	Maximum internal global clock frequency	(2), (4)	222.2		135.1		100.0		MHz
t _{acnt}	Minimum array clock period	(2)		4.5		7.4		10.0	ns
f _{acnt}	Maximum internal array clock frequency	(2), (4)	222.2		135.1		100.0		MHz

Table 20. EPM7064AE Internal Timing Parameters (Part 2 of 2) Note (1)										
Symbol	Parameter	Conditions	Speed Grade							
			-	-4		7	-10			
			Min	Max	Min	Max	Min	Max		
t _{EN}	Register enable time			0.6		1.0		1.2	ns	
t _{GLOB}	Global control delay			1.0		1.5		2.2	ns	
t _{PRE}	Register preset time			1.3		2.1		2.9	ns	
t _{CLR}	Register clear time			1.3		2.1		2.9	ns	
t _{PIA}	PIA delay	(2)		1.0		1.7		2.3	ns	
t _{LPA}	Low-power adder	(6)		3.5		4.0		5.0	ns	

Symbol	Parameter	Conditions			Speed	Grade			Unit
			-	5	-	7	-1	0	
			Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non- registered output	C1 = 35 pF (2)		5.0		7.5		10	ns
t _{PD2}	I/O input to non- registered output	C1 = 35 pF (2)		5.0		7.5		10	ns
t _{SU}	Global clock setup time	(2)	3.3		4.9		6.6		ns
t _H	Global clock hold time	(2)	0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		2.5		3.0		3.0		ns
t _{FH}	Global clock hold time of fast input		0.0		0.0		0.0		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF	1.0	3.4	1.0	5.0	1.0	6.6	ns
t _{CH}	Global clock high time		2.0		3.0		4.0		ns
t _{CL}	Global clock low time		2.0		3.0		4.0		ns
t _{ASU}	Array clock setup time	(2)	1.8		2.8		3.8		ns
t _{AH}	Array clock hold time	(2)	0.2		0.3		0.4		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF (2)	1.0	4.9	1.0	7.1	1.0	9.4	ns
t _{ACH}	Array clock high time		2.0		3.0		4.0		ns
t _{ACL}	Array clock low time		2.0		3.0		4.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(3)	2.0		3.0		4.0		ns
t _{CNT}	Minimum global clock period	(2)		5.2		7.7		10.2	ns
fcnt	Maximum internal global clock frequency	(2), (4)	192.3		129.9		98.0		MHz
t _{acnt}	Minimum array clock period	(2)		5.2		7.7		10.2	ns
f _{acnt}	Maximum internal array clock frequency	(2), (4)	192.3		129.9		98.0		MHz

Symbol	Parameter	Conditions			Speed	Grade			Unit
			-	5	-	7		10	
			Min	Max	Min	Max	Min	Max	
t _{IN}	Input pad and buffer delay			0.7		1.0		1.4	ns
t _{IO}	I/O input pad and buffer delay			0.7		1.0		1.4	ns
t _{FIN}	Fast input delay			2.5		3.0		3.4	ns
t _{SEXP}	Shared expander delay			2.0		2.9		3.8	ns
t _{PEXP}	Parallel expander delay			0.4		0.7		0.9	ns
t _{LAD}	Logic array delay			1.6		2.4		3.1	ns
t _{LAC}	Logic control array delay			0.7		1.0		1.3	ns
t _{IOE}	Internal output enable delay			0.0		0.0		0.0	ns
t _{OD1}	Output buffer and pad delay, slow slew rate = off $V_{CCIO} = 3.3 V$	C1 = 35 pF		0.8		1.2		1.6	ns
t _{OD2}	Output buffer and pad delay, slow slew rate = off $V_{CCIO} = 2.5 V$	C1 = 35 pF (5)		1.3		1.7		2.1	ns
t _{OD3}	Output buffer and pad delay, slow slew rate = on $V_{CCIO} = 2.5 V \text{ or } 3.3 V$	C1 = 35 pF		5.8		6.2		6.6	ns
t _{ZX1}	Output buffer enable delay, slow slew rate = off $V_{CCIO} = 3.3 V$	C1 = 35 pF		4.0		4.0		5.0	ns
t _{ZX2}	Output buffer enable delay, slow slew rate = off $V_{CCIO} = 2.5 V$	C1 = 35 pF (5)		4.5		4.5		5.5	ns
t _{ZX3}	Output buffer enable delay, slow slew rate = on $V_{CCIO} = 3.3 V$	C1 = 35 pF		9.0		9.0		10.0	ns
t _{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0		5.0	ns
t _{SU}	Register setup time		1.4		2.1		2.9		ns
t _H	Register hold time		0.6		1.0		1.3		ns
t _{FSU}	Register setup time of fast input		1.1		1.6		1.6		ns
t _{FH}	Register hold time of fast input		1.4		1.4		1.4		ns
t _{RD}	Register delay			0.8		1.2		1.6	ns
t _{COMB}	Combinatorial delay			0.5		0.9		1.3	ns
t _{IC}	Array clock delay			1.2		1.7		2.2	ns

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Table 22. EPM7128AE Internal Timing Parameters (Part 2 of 2) Note (1)											
Symbol	Parameter	Conditions	Speed Grade								
			-	-5		7	-10				
			Min	Max	Min	Max	Min	Max			
t _{EN}	Register enable time			0.7		1.0		1.3	ns		
t _{GLOB}	Global control delay			1.1		1.6		2.0	ns		
t _{PRE}	Register preset time			1.4		2.0		2.7	ns		
t _{CLR}	Register clear time			1.4		2.0		2.7	ns		
t _{PIA}	PIA delay	(2)		1.4		2.0		2.6	ns		
t _{LPA}	Low-power adder	(6)		4.0		4.0		5.0	ns		

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Symbol	Parameter	Conditions			Speed	Grade			Unit
			-	5	-	7		10	
			Min	Max	Min	Max	Min	Max	
t _{IN}	Input pad and buffer delay			0.7		0.9		1.2	ns
t _{IO}	I/O input pad and buffer delay			0.7		0.9		1.2	ns
t _{FIN}	Fast input delay			2.4		2.9		3.4	ns
t _{SEXP}	Shared expander delay			2.1		2.8		3.7	ns
t _{PEXP}	Parallel expander delay			0.3		0.5		0.6	ns
t _{LAD}	Logic array delay			1.7		2.2		2.8	ns
t _{LAC}	Logic control array delay			0.8		1.0		1.3	ns
t _{IOE}	Internal output enable delay			0.0		0.0		0.0	ns
t _{OD1}	Output buffer and pad delay, slow slew rate = off $V_{CCIO} = 3.3 V$	C1 = 35 pF		0.9		1.2		1.6	ns
t _{OD2}	Output buffer and pad delay, slow slew rate = off $V_{CCIO} = 2.5 V$	C1 = 35 pF (5)		1.4		1.7		2.1	ns
t _{OD3}	Output buffer and pad delay, slow slew rate = on $V_{CCIO} = 2.5 V \text{ or } 3.3 V$	C1 = 35 pF		5.9		6.2		6.6	ns
t _{ZX1}	Output buffer enable delay, slow slew rate = off $V_{CCIO} = 3.3 V$	C1 = 35 pF		4.0		4.0		5.0	ns
t _{ZX2}	Output buffer enable delay, slow slew rate = off $V_{CCIO} = 2.5 V$	C1 = 35 pF (5)		4.5		4.5		5.5	ns
t _{ZX3}	Output buffer enable delay, slow slew rate = on $V_{CCIO} = 3.3 V$	C1 = 35 pF		9.0		9.0		10.0	ns
t _{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0		5.0	ns
t _{SU}	Register setup time		1.5		2.1		2.9		ns
t _H	Register hold time		0.7		0.9		1.2		ns
t _{FSU}	Register setup time of fast input		1.1		1.6		1.6		ns
t _{FH}	Register hold time of fast input		1.4		1.4		1.4		ns
t _{RD}	Register delay			0.9		1.2		1.6	ns
t _{COMB}	Combinatorial delay			0.5		0.8		1.2	ns

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Symbol	Parameter	Conditions				Speed	Grade				Unit
			-	6	-	7	-1	10	-1	12	
			Min	Max	Min	Max	Min	Мах	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF (2)		6.0		7.5		10.0		12.0	ns
t _{PD2}	I/O input to non- registered output	C1 = 35 pF (2)		6.0		7.5		10.0		12.0	ns
t _{SU}	Global clock setup time	(2)	4.2		5.3		7.0		8.5		ns
t _H	Global clock hold time	(2)	0.0		0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		2.5		3.0		3.0		3.0		ns
t _{FH}	Global clock hold time of fast input		0.0		0.0		0.0		0.0		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF	1.0	3.7	1.0	4.6	1.0	6.1	1.0	7.3	ns
t _{CH}	Global clock high time		3.0		3.0		4.0		5.0		ns
t _{CL}	Global clock low time		3.0		3.0		4.0		5.0		ns
t _{ASU}	Array clock setup time	(2)	1.9		2.4		3.1		3.8		ns
t _{AH}	Array clock hold time	(2)	1.5		2.2		3.3		4.3		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF (2)	1.0	6.0	1.0	7.5	1.0	10.0	1.0	12.0	ns
t _{ACH}	Array clock high time		3.0		3.0		4.0		5.0		ns
t _{ACL}	Array clock low time		3.0		3.0		4.0		5.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(3)	3.0		3.0		4.0		5.0		ns
t _{CNT}	Minimum global clock period	(2)		6.9		8.6		11.5		13.8	ns
f _{CNT}	Maximum internal global clock frequency	(2), (4)	144.9		116.3		87.0		72.5		MHz
t _{acnt}	Minimum array clock period	(2)		6.9		8.6		11.5		13.8	ns
f _{acnt}	Maximum internal array clock frequency	(2), (4)	144.9		116.3		87		72.5		MHz

Symbol	Parameter	Conditions	Speed Grade								
			-6		6 -7		-10		-12]
			Min	Мах	Min	Max	Min	Мах	Min	Max	
t _{COMB}	Combinatorial delay			1.6		2.0		2.7		3.2	ns
t _{IC}	Array clock delay			2.7		3.4		4.5		5.4	ns
t _{EN}	Register enable time			2.5		3.1		4.2		5.0	ns
t _{GLOB}	Global control delay			1.1		1.4		1.8		2.2	ns
t _{PRE}	Register preset time			2.3		2.9		3.8		4.6	ns
t _{CLR}	Register clear time			2.3		2.9		3.8		4.6	ns
t _{PIA}	PIA delay	(2)		1.3		1.6		2.1		2.6	ns
t _{LPA}	Low-power adder	(6)		11.0		10.0		10.0		10.0	ns

Table 30. EPM7256A Internal Timing Parameters (Part 2 of 2) Note (1)

Notes to tables:

 These values are specified under the recommended operating conditions shown in Table 14 on page 28. See Figure 12 for more information on switching waveforms.

- (2) These values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (3) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (4) This parameter is measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) Operating conditions: $V_{CCIO} = 2.5 \pm 0.2$ V for commercial and industrial use.
- (6) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , $\mathbf{t_{ACL}}$, and $\mathbf{t_{CPPW}}$ parameters for macrocells running in low-power mode.

Power Consumption

Supply power (P) versus frequency (f_{MAX} , in MHz) for MAX 7000A devices is calculated with the following equation:

 $P = P_{INT} + P_{IO} = I_{CCINT} \times V_{CC} + P_{IO}$

The P_{IO} value, which depends on the device output load characteristics and switching frequency, can be calculated using the guidelines given in *Application Note* 74 (*Evaluating Power for Altera Devices*).

The I_{CCINT} value depends on the switching frequency and the application logic. The I_{CCINT} value is calculated with the following equation:

I_{CCINT} =

 $(A \times MC_{TON}) + [B \times (MC_{DEV} - MC_{TON})] + (C \times MC_{USED} \times f_{MAX} \times tog_{LC})$

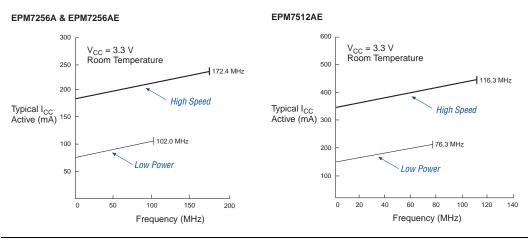


Figure 13. I_{CC} vs. Frequency for MAX 7000A Devices (Part 2 of 2)

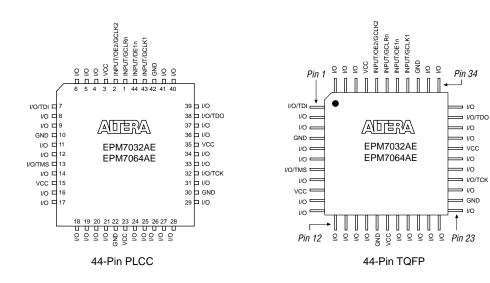
Device Pin-Outs

See the Altera web site (http://www.altera.com) or the *Altera Digital Library* for pin-out information.

Figures 14 through 23 show the package pin-out diagrams for MAX 7000A devices.

Figure 14. 44-Pin PLCC/TQFP Package Pin-Out Diagram

Package outlines not drawn to scale.



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Figure 17. 100-Pin TQFP Package Pin-Out Diagram

Package outline not drawn to scale.

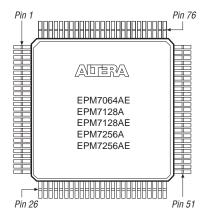


Figure 18. 100-Pin FineLine BGA Package Pin-Out Diagram

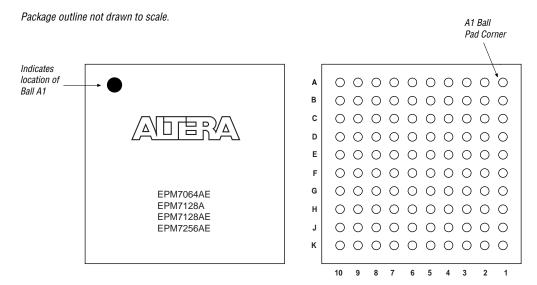


Figure 22. 256-Pin BGA Package Pin-Out Diagram

Package outline not drawn to scale.

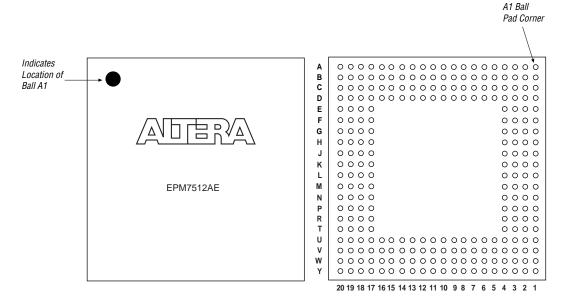
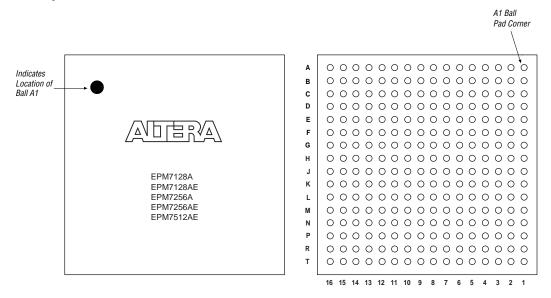


Figure 23. 256-Pin FineLine BGA Package Pin-Out Diagram

Package outline not drawn to scale.



Revision History

The information contained in the *MAX 7000A Programmable Logic Device Data Sheet* version 4.5 supersedes information published in previous versions.

Version 4.5

The following changes were made in the *MAX 7000A Programmable Logic Device Data Sheet* version 4.5:

■ Updated text in the "Power Sequencing & Hot-Socketing" section.

Version 4.4

The following changes were made in the *MAX 7000A Programmable Logic Device Data Sheet* version 4.4:

- Added Tables 5 through 7.
 - Added "Programming Sequence" on page 17 and "Programming Times" on page 18.

Version 4.3

The following changes were made in the *MAX 7000A Programmable Logic Device Data Sheet* version 4.3:

- Added extended temperature devices to document
- Updated Table 14.

Version 4.2

The following changes were made in the *MAX 7000A Programmable Logic Device Data Sheet* version 4.2:

- Removed *Note* (1) from Table 2.
- Removed *Note* (4) from Tables 3 and 4.

Version 4.1

The following changes were made in the *MAX 7000A Programmable Logic Device Data Sheet* version 4.1:

- Updated leakage current information in Table 15.
- Updated Note (9) of Table 15.
- Updated *Note* (1) of Tables 17 through 30.



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